

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IR35412MTRPBF	**Issued**	04. April 2021
MA#	MA001688066		
Package	PG-IQFN-39-4	**Weight***	113.13 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.966	0.85	0.85	8538	8538
chip_2	inorganic material	silicon	7440-21-3	0.261	0.23	0.23	2311	2311
chip_3	inorganic material	silicon	7440-21-3	1.538	1.36	1.36	13597	13597
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		101	
	non noble metal	zinc	7440-66-6	0.046	0.04		405	
	non noble metal	iron	7439-89-6	0.917	0.81		8102	
	non noble metal	copper	7440-50-8	37.219	32.90	33.76	328995	337603
wire	non noble metal	copper	7440-50-8	0.145	0.13	0.13	1280	1280
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		734	
	plastics	epoxy resin	-	4.274	3.78		37782	
	inorganic material	silicondioxide	60676-86-0	37.140	32.83	36.68	328300	366816
leadfinish	noble metal	palladium	7440-05-3	0.000			2	
	noble metal	gold	7440-57-5	0.000			4	
	non noble metal	nickel	7440-02-0	0.007	0.01	0.01	64	70
plating	noble metal	silver	7440-22-4	0.967	0.85	0.85	8546	8546
solder	noble metal	silver	7440-22-4	0.085	0.08		754	
	non noble metal	tin	7440-31-5	0.171	0.15		1509	
	non noble metal	lead	7439-92-1	3.158	2.79	3.02	27914	30177
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.008	0.01		69	
	non noble metal	iron	7439-89-6	0.026	0.02		231	
	non noble metal	copper	7440-50-8	26.106	23.08	23.11	230762	231062
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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